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SEMATECH Surface Preparation and Cleaning Conference
March 2&-24, 2010

Tuesday, March 23rd

F **KEYNOTE: Creative Collaboration: New Directions for Our Industry**
Daniel Armbrust (SEMATECH)

G **INVITED: ITRS 2009 FEP Chapter: Upcoming Challenges in Transistor Scaling**
Jeff Butterbaugh (FSI International)

Gĺ **INVITED: Emerging Technology: New Surface Preparation and Clean Challenges**
Casey Smith (SEMATECH)

I Ï ÁÁ …**Dry Etch Processing of Microelectronic Devices with HF/H_2O/Supercritical CO_2**
Kwon Taek Lim (Pukyong National University)

Î Ì **Investigation of Wet Etch of sub-nm LaOx Capping Layers for CMOS applications**
Mohamad Jahanbani (CNSE)

Ì G **Bond pad Surface Quality for Reliable Wire Bonding**
Martin Knotter (NXP Semiconductors)

JJ **INVITED: III-V MOSFETs - Opportunities and Challenges**
Richard Hill (SEMATECH)

FGF **INVITED: The Next Generation of Metrology: Surface-Sensitive Characterization Techniques for High Mobility Channel Materials**
Jimmy Price (SEMATECH)

FHÎ **INVITED: Water Management on Semiconductor Surfaces**
Yannick Le Tiec (CEA-LETI)

FÎ I **Nanoscale Particle Removal Using Wet Laser Shockwave Cleaning**
Tae Hoon Kim (Northeastern University)

FÌ J **Turning enemies into friends: Controllable Collapsing Bubbles as a Novel Approach for NANO Scale Wafer Cleaning and Surface Preparation**
Yehiel Gotkis (KaVeNaki)

G€Ï **Control Of Sonoluminescence Signal In Di Water Using Carbon Dioxide**
Sangita Kumari (University of Arizona)

GGG **Controlled DI Water CO_2 Gasification to Eliminate ESD Effects and Corrosion - Control of Contamination, Development in Equipments**
Chris Gottschalk (ASTeX GmbH)

GHÌ **Atmospheric EHD Cleaning Chamber Yields High PRE**
Ken Finster (EHD Technology Group)

Wednesday, March 24th

GÍ Ï **INVITED: Opportunities for Recycling and Reclaiming Fab and Assembly Test Facility Wastewaters – A Benchmarking Study**
Michael Frisch (ISMI)

GÌ I **Chemical Supply Cost Reduction: Gauging today's Risk in Modern Fabs**
Byron Palla (Texas Instruments)

H€G **INVITED: Challenges on BEOL Wafer Cleaning**
Bob Small (Bob Small Associates)

HGH **The Effects of Surface Roughness and Chemistry on SiO_2 and Low-k Film Wetting**
Rick Reidy (University of North Texas)

HI F **INVITED: Cu Post-CMP Cleaners: Why Are Formulated Products Necessary and How Does One Design a Commercially Successful Cu Post-CMP Cleaner?**
Darryl Peters (Confluense)

HÎ Í **Additives to Reduce Small Particle Defects in Post-CMP Cleaning**
Paul Bernatis (EKC)

HJ€ **Charge-Induced Attraction of Particles in Post CMP and Megasonic Clean Processes**
` Yuji Yamada (Toshiba)

I FI **Evaluation of Cleaning Procedure for the Detection of Scratches Formed on Oxide Wafer during CMP Process**
Jin-Goo Park (Hanyang University)

I HH **Cold Implanted Resist Modeling**
Allan Upham (IBM)

I I H **All-Wet Removal of Post-Etch Photoresist and Sidewall Residues: Electrical Characterization of 90 nm and 30 nm ½ Pitch Structures**
Quoc Toan Le (IMEC)

I Î I **Thermal Wafer for WETS Optimization**
Allan Upham (IBM) Upham POR, Upham BKM

I Ï Í **Pushing the Piranha Chemistry to Strip Higher Dosed Photoresist**
Dusty Leonhard (Semitool)

I JG **Post-Etch Sidewall Residues in Metal Hard Mask/Porous Low-k Single Damascene Structures: Characterization and Wet Removal**
Quoc Toan Le (IMEC)

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